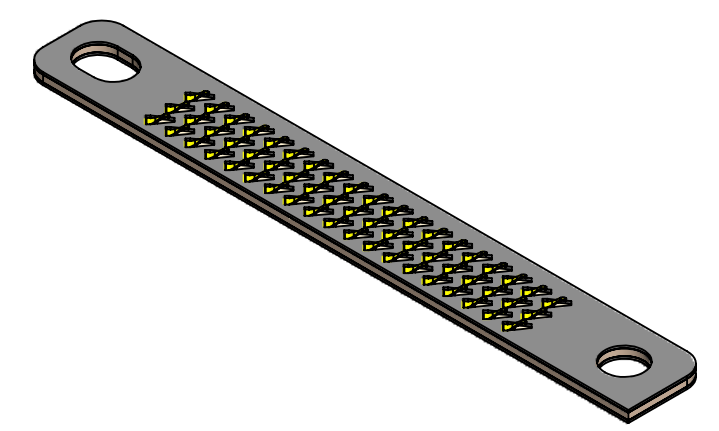
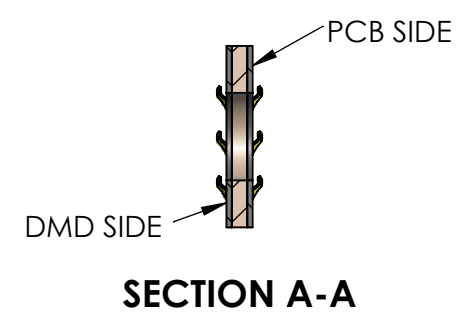
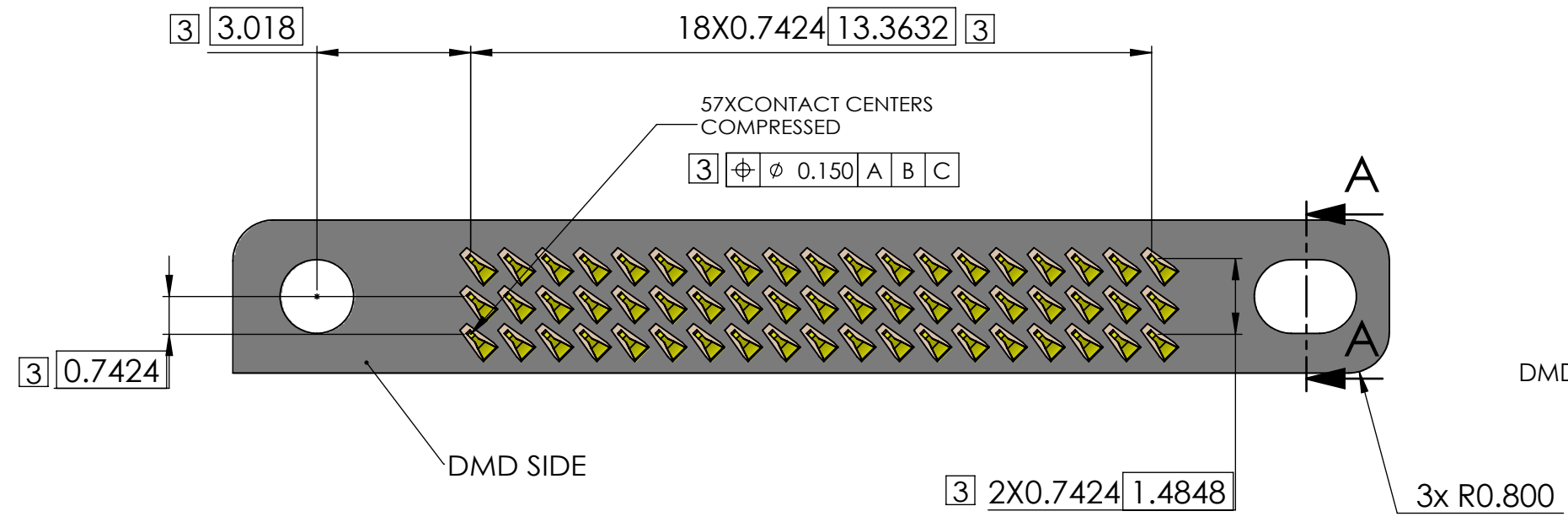
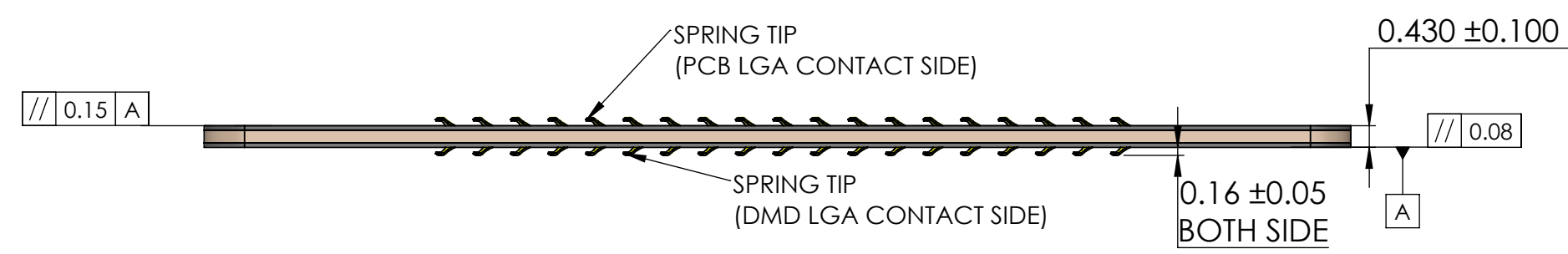
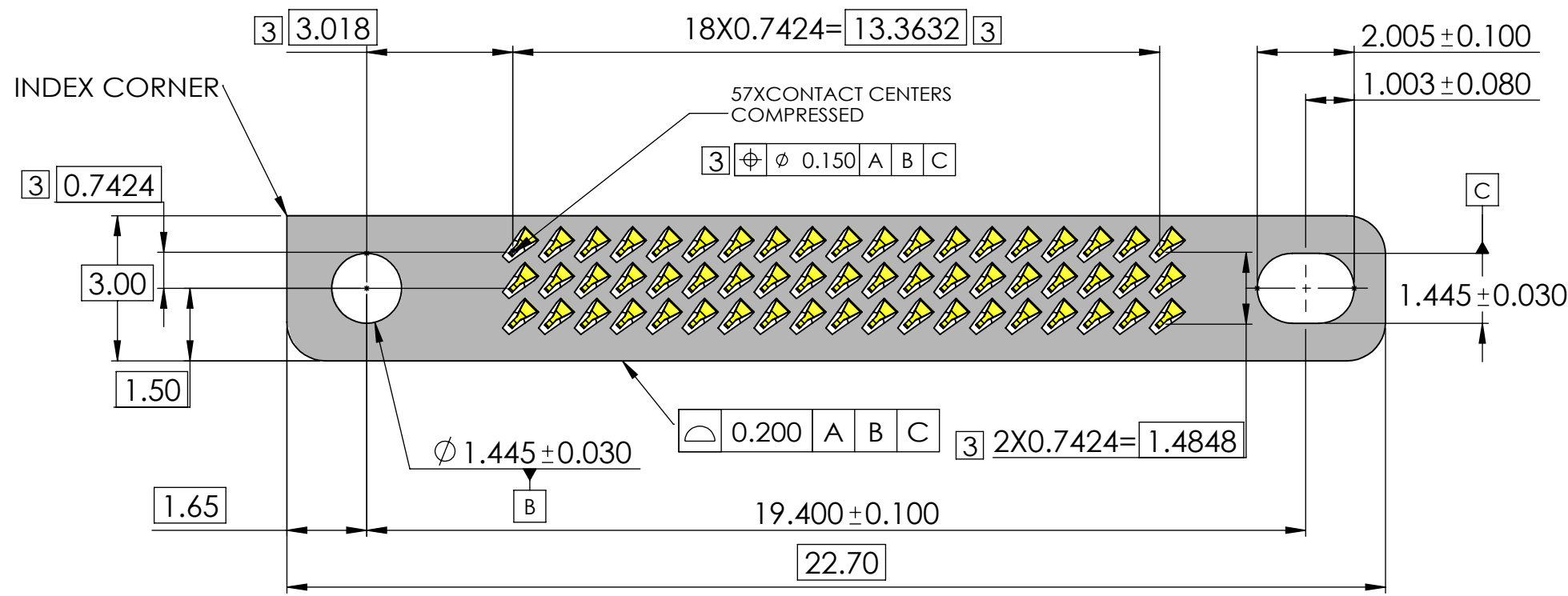


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PERMISSION OF NEOCONIX.

REVISIONS				
REV	ECO	DESCRIPTION	DATE	APPROVED
A		New release	07/24/2018	HM

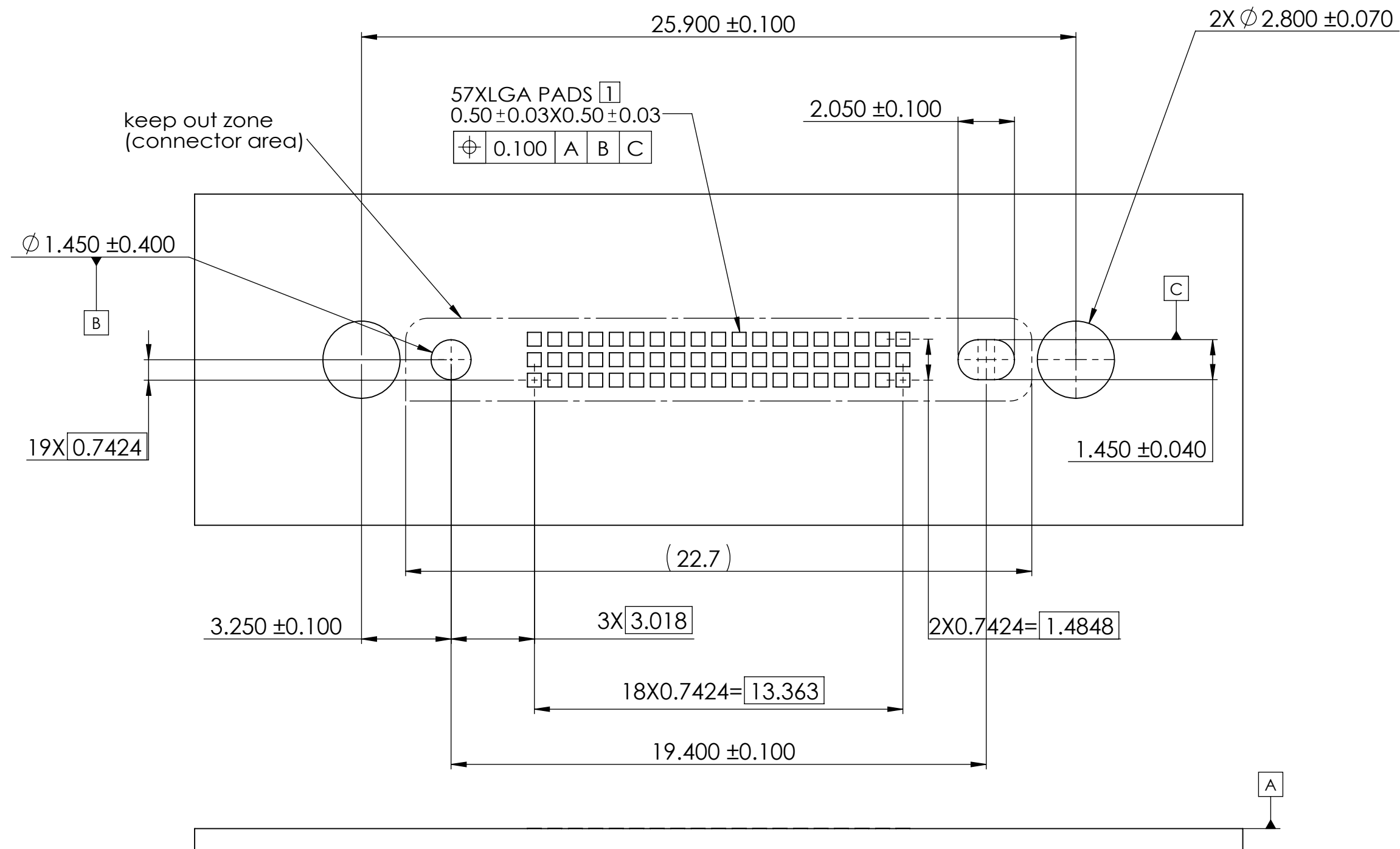


NOTES (UNLESS OTHERWISE SPECIFIED) :

- INTERPOSER DRAWING PER ASME Y14.5-1994
- COMPLIANT WITH RoHS DIRECTIVE 2002/95/EC
- CENTER MARKS OF CONTACT POSITIONS ARE FOR COMPRESSED STATE

<p>4020 MOORPARK AVE., SUITE 108. SAN JOSE, CA 95117 TEL: 408-530-9393 FAX: 408-530-9383</p>	<p>DIMENSIONS ARE IN MM [INCH]</p> <p>.X ± 0.13 [.005] .XX ± 0.08 [.003] .XXX ± 0.025 [.001]</p> <p>ANGLE: NO DEC ± 1° .X ± 0.5° .XX ± 0.25°</p>	<p>MATERIAL: SEE NOTES</p> <p>FINISH: --</p>	<p>TITLE: 57 POS PCBeam DMD Interposer (Low-Height) LGA-LGA, 0.7424 Pitch</p>
	<p>DRAWN BY: HEMING 2018/7/26</p> <p>CHECKED BY: Gary Hsieh 2018/7/26</p> <p>ENGR APPR: Gary Hsieh 2018/7/26</p> <p>MFG APPR:</p> <p>QA APPR:</p>	<p>SIZE: B+</p> <p>DWG NUMBER: BDX0057CMMF4AU03</p>	<p>REV: A</p>
	<p>THIRD ANGLE</p>	<p>SCALE: 8:1</p>	<p>SHEET 1 OF 2</p>
	<p>SCALE: 8:1 SHEET 1 OF 2</p>		

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Recommend PCB footprint

Notes(UNLESS OTHERWISE SPECIFIED):

1 PADS TO BE ELECTROLESS NICKEL/IMMERSION GOLD(ENIG) PLATED.

neconix
4020 Moorpark Ave., #108
San Jose, CA 95117
TEL: 408-530-9393 FAX: 408-530-9383

DIMENSIONS ARE IN
mm [INCH]
.X ± 0.13 [.005]
.XX ± 0.08 [.003]
.XXX ± 0.025 [.001]
ANGLE: NO DEC ± 1°
.X ± 0.5°
.XX ± 0.25°



MATERIAL: Gold
FINISH: --
DRAWN BY: Heming 2018/7/26
CHECKED BY: Gary Hsieh 2018/7/26
ENGR APPR: Gary Hsieh 2018/7/26
MFG APPR:
QA APPR:

TITLE: RECOMMENDED PCB

SIZE: B+ DWG NUMBER: BDX0057CMMF4AU03 REV: A

SCALE: 5:1 SHEET 2 OF 2